



A Product Line of Diodes Incorporated



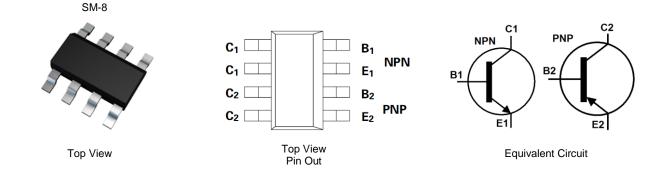
100V COMPLEMENTARY MEDIUM POWER TRANSISTOR IN SM-8

Features

- NPN Transistor
 - BV_{CEO} > 100
 - I_C = 2A High Continuous Current
 - Low Saturation Voltage V_{CE(sat)} < 300mV @ 1A
- PNP Transistor
 - BV_{CEO} > -100V
 - I_C = -2A High Continuous Current
 - Low Saturation Voltage V_{CE(sat)} < -300mV @ -1A
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SM-8 (8 LEAD SOT223)
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads. Solderable per MIL-STD-202, Method 208 (€3)
- Weight: 0.117 grams (Approximate)



Ordering Information (Note 4)

| Part Number | Marking | Reel size (inches) | Tape width (mm) | Quantity per reel |
|-------------|---------|--------------------|-----------------|-------------------|
| ZDT6753TA | T6753 | 7 | 12 | 1,000 |
| ZDT6753TC | T6753 | 13 | 12 | 4,000 |

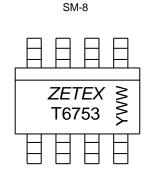
Notes: 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.

2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



T6753 = Product Type Marking Code YWW = Date Code Marking Y or \overline{Y} = Last Digit of Year (ex: 5= 2015) WW or $\overline{W}W$ = Week Code (01~53)





Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | NPN | PNP | Unit |
|------------------------------|------------------|-----|------|------|
| Collector-Base Voltage | V _{CBO} | 120 | -120 | V |
| Collector-Emitter Voltage | V _{CEO} | 100 | -100 | V |
| Emitter-Base Voltage | V _{EBO} | 7 | -7 | V |
| Continuous Collector Current | Ι _C | 2 | -2 | A |
| Peak Pulse Current (Note 5) | I _{CM} | 6 | -6 | A |

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit | | |
|--|----------|----------------------------------|-------------|------|--|
| Collector Power Dissipation | (Note 5) | р | 2.25 | W | |
| Collector Fower Dissipation | (Note 6) | P _D | 2.75 | | |
| Thermal Desistance, Junction to Ambient | (Note 5) | D | 55.6 | °C/W | |
| Thermal Resistance, Junction to Ambient | (Note 6) | R _{0JA} | 45.5 | C/VV | |
| Thermal Resistance, Junction to Leads (Note 7) | | R _{θJL} | 30.7 | °C/W | |
| Operating and Storage Temperature Range | | T _J ,T _{STG} | -55 to +150 | °C | |

ESD Ratings (Note 8)

| Characteristic | Symbol | Value | Unit | JEDEC Class |
|--|---------|-------|------|-------------|
| Electrostatic Discharge - Human Body Model | ESD HBM | 4,000 | V | 3A |
| Electrostatic Discharge - Machine Model | ESD MM | 400 | V | С |

5. For a device with any single die active and mounted with the collector lead on 25mm x 25mm 2oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady-state. Notes:

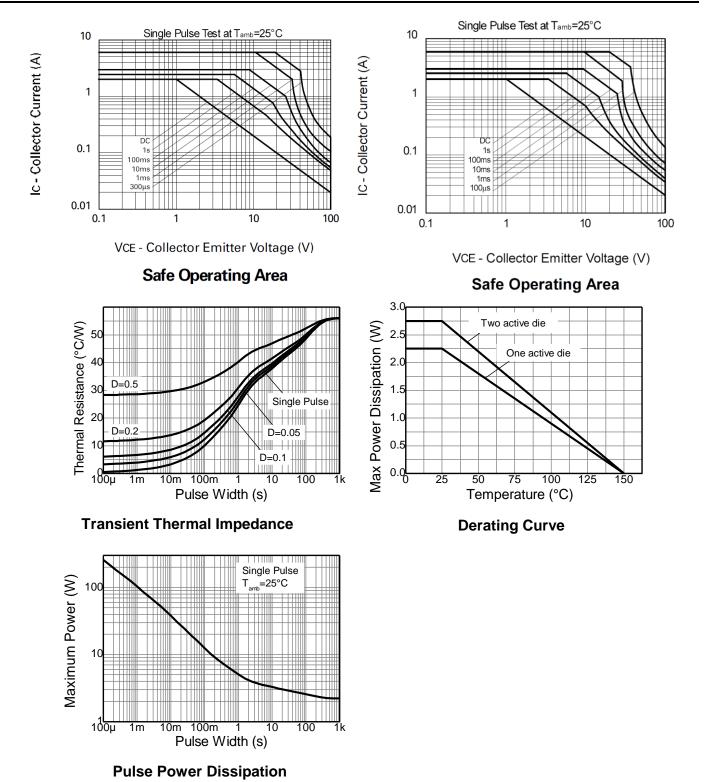
6. Same as Note 5, except both die are active and equally sharing power.

Thermal resistance from junction to solder-point (at the end of the collector lead).
Refer to JEDEC specification JESD22-A114 and JESD22-A115.





Thermal Characteristics and Derating Information







| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition |
|---|----------------------|-----|------|------|------|---|
| Collector-Base Breakdown Voltage | BV _{CBO} | 120 | — | _ | V | I _C = 100μA |
| Collector-Emitter Breakdown Voltage (Note 9) | BV _{CEO} | 100 | — | — | V | $I_{\rm C} = 10 {\rm mA}$ |
| Emitter-Base Breakdown Voltage | BV _{EBO} | 7 | — | — | V | I _E = 100μA |
| Collector Cut-Off Current | | _ | < 1 | 0.1 | μA | V _{CB} = 100V |
| | I _{CBO} | _ | — | 10 | μA | V _{CB} = 100V, T _A = +125°C |
| Emitter Cut-Off Current | I _{EBO} | _ | < 1 | 0.1 | μA | V _{EB} = 5.6V |
| | h _{FE} | 70 | 200 | — | | $I_C = 50 \text{mA}, V_{CE} = 2 \text{V}$ |
| DC Current Transfer Static Datic (Nate 0) | | 100 | 200 | 300 | | $I_{C} = 500 \text{mA}, V_{CE} = 2 \text{V}$ |
| DC Current Transfer Static Ratio (Note 9) | | 55 | 110 | — | | $I_{C} = 1A, V_{CE} = 2V$ |
| | | 25 | 55 | _ | | $I_{C} = 2A, V_{CE} = 2V$ |
| | V _{CE(sat)} | _ | 0.13 | 0.30 | V | $I_{\rm C} = 1$ A, $I_{\rm B} = 100$ mA |
| Collector-Emitter Saturation Voltage (Note 9) | | _ | 0.23 | 0.50 | | $I_{\rm C} = 2A, I_{\rm B} = 200 {\rm mA}$ |
| Base-Emitter Saturation Voltage (Note 9) | V _{BE(sat)} | _ | 0.9 | 1.25 | V | I _C = 1A, I _B = 100mA |
| Base-Emitter Turn-on Voltage (Note 9) | V _{BE(on)} | _ | 0.8 | 1.0 | V | $I_{C} = 1A, V_{CE} = 2V$ |
| Transitional Frequency | f _T | 140 | 175 | _ | MHz | $I_{C} = 100 \text{mA}, V_{CE} = 5 \text{V},$ f = 100MHz |
| Output Capacitance | C _{obo} | — | _ | 30 | pF | V _{CB} = 10V, f = 1MHz |
| | t _{on} | — | 80 | _ | Ns | $V_{CC} = 10V, I_C = 500mA,$ |
| Switching Time | t _{off} | — | 1200 | _ | ns | $I_{B1} = -I_{B2} = 50 \text{mA}$ |

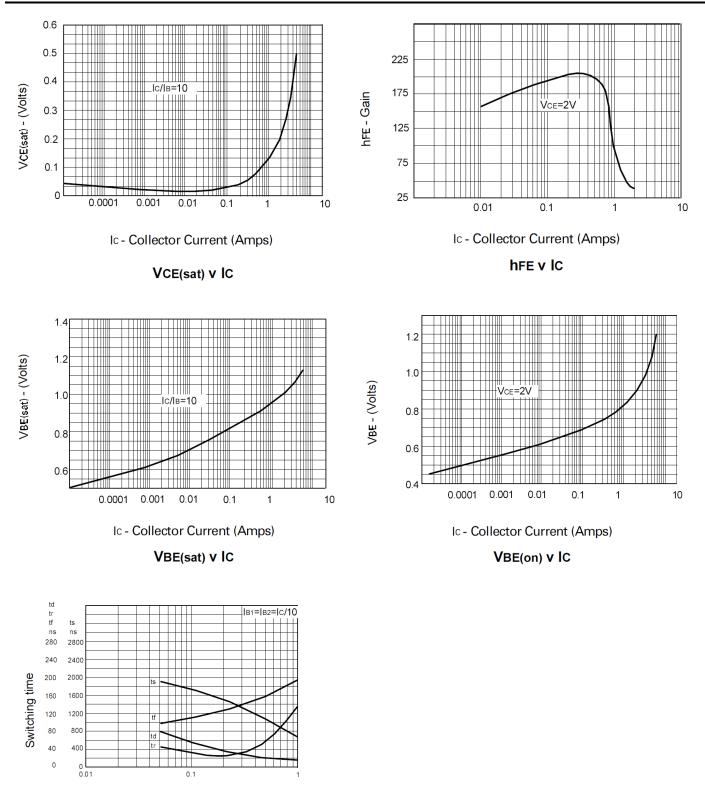
NPN - Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Note: 9. Measured under pulsed conditions. Pulse width \leq 300µs. Duty cycle \leq 2%.





NPN – Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)



Ic - Collector Current (Amps)

Switching Speeds



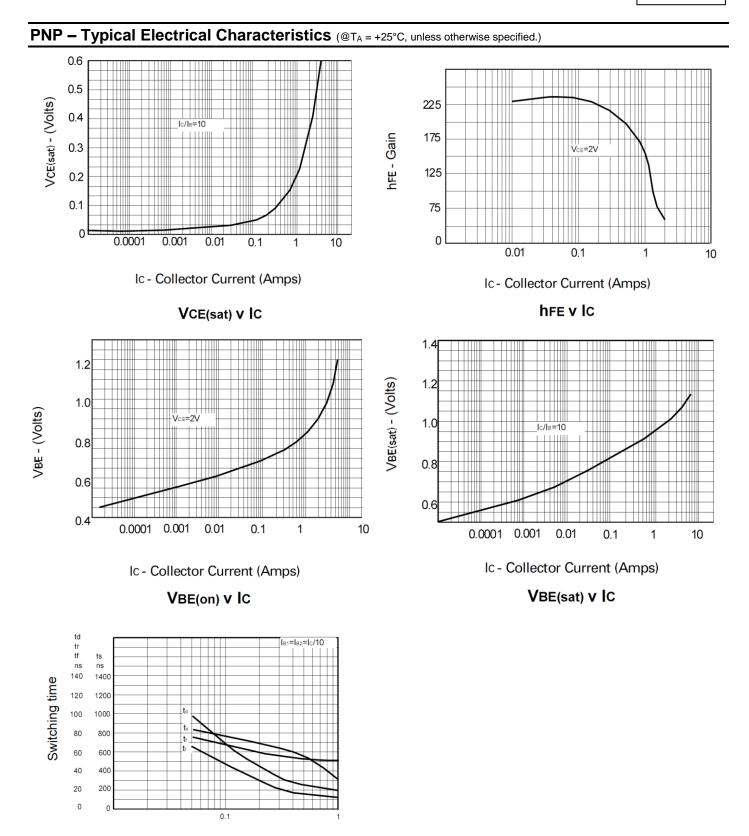


PNP - Electrical Characteristics (@T_A = +25°C, unless otherwise specified.) **Test Condition** Min Unit Characteristic Symbol Тур Max -120 V Collector-Base Breakdown Voltage $\mathsf{BV}_{\mathsf{CBO}}$ $I_{C} = -100 \mu A$ Collector-Emitter Breakdown Voltage (Note 9) -100 V ___ _ $I_C = -10 \text{mA}$ **BV**CEO Emitter-Base Breakdown Voltage -7 ٧ $I_{E} = -100 \mu A$ BV_{EBO} ____ _____ _ μΑ $V_{CB} = -100V$ -0.1 < 1 Collector Cut-Off Current I_{CBO} $V_{CB} = -100V, T_A = +125^{\circ}C$ -10 μA _ ____ Emitter Cut-Off Current < 1 -0.1 μΑ $V_{EB} = -5.6V$ IEBO _ 70 200 $I_{C} = -50 \text{mA}, V_{CE} = -2 \text{V}$ 200 300 100 $I_{C} = -500 \text{mA}, V_{CE} = -2 \text{V}$ DC Current Transfer Static Ratio (Note 8) h_{FE} 55 170 $I_C = -1A$, $V_{CE} = -2V$ — $I_C = -2A$, $V_{CE} = -2V$ 25 55 ____ -0.17 -0.30 ____ $I_{C} = -1A, I_{B} = -100mA$ Collector-Emitter Saturation Voltage (Note 9) V V_{CE(sat)} -0.30 -0.50 $I_{C} = -2A, I_{B} = -200mA$ Base-Emitter Saturation Voltage (Note 9) -0.90 -1.25 V $I_{C} = -1A, I_{B} = -100mA$ V_{BE(sat)} _ Base-Emitter Turn-On Voltage (Note 9) V -0.80 -1.0 $I_{C} = -1A, V_{CE} = -2V$ V_{BE(on)} ____ $I_{C} = -100 \text{mA}, V_{CE} = -5 \text{V},$ Transitional Frequency f⊤ 100 140 MHz ____ f = 100MHzOutput Capacitance Cobo 30 $V_{CB} = -10V, f = 1MHz,$ pF ____ 35 ton ns $V_{CC} = -10V, I_{C} = -500mA,$ Switching Time 600 $I_{B1} = -I_{B2} = -50 \text{mA}$ ns \mathbf{t}_{off}

Note: 9. Measured under pulsed conditions. Pulse width \leq 300µs. Duty cycle \leq 2%.







Ic - Collector Current (Amps)

Switching Speeds

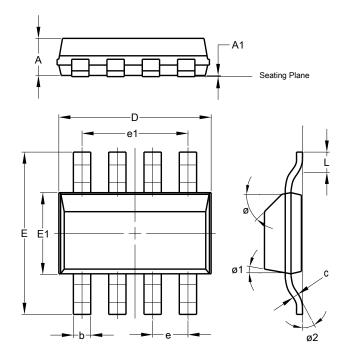
ZDT6753 Document number: DS33209 Rev. 3 - 2 Downloaded from Arrow.com.





Package Outline Dimensions

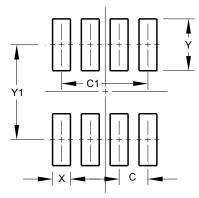
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



| | SM-8 | | | | |
|-------|----------------------|------|------|--|--|
| Dim | Min Max Typ | | | | |
| Α | | 1.70 | 1.60 | | |
| A1 | 0.02 | 0.10 | 0.04 | | |
| b | 0.70 | 0.90 | 0.80 | | |
| c | 0.24 | 0.32 | 0.28 | | |
| D | 6.30 | 6.70 | 6.60 | | |
| e | 1.53 REF | | | | |
| e1 | 4.59 REF | | | | |
| Е | 6.70 | 7.30 | 7.00 | | |
| E1 | 3.30 | 3.70 | 3.50 | | |
| L | 0.75 | 1.00 | 0.90 | | |
| Ø | 45° | | | | |
| Ø1 | | 15° | | | |
| Ø2 | | | 10° | | |
| All I | All Dimensions in mm | | | | |

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| С | 1.52 |
| C1 | 4.6 |
| Х | 0.95 |
| Y | 2.80 |
| Y1 | 6.80 |

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.





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